2.5-V 460-kbps RS-232 TRANSCEIVER WITH ±15-kV ESD PROTECTION

Check for Samples: MAX3318

FEATURES

- **ESD Protection for RS-232 I/O Pins**
  - **±15 kV (Human-Body Model)**
  - **±8 kV (IEC 61000-4-2, Contact Discharge)**
  - **±8 kV (IEC 61000-4-2, Air-Gap Discharge)**
- **300-µA Operating Supply Current**
- **1-µA Low-Power Standby (With Receivers Active) Mode**
- **Designed to Transmit at a Data Rate of 460 kbps**
- **Auto-Power-Down Plus Option Features Flexible Power-Saving Mode**
- **Operates From a Single 2.25-V to 3-V V_{CC} Supply**

APPLICATIONS

- **Battery-Powered Systems**
- **PDAs**
- **Cellular Phones**
- **Notebooks**
- **Hand-Held Equipment**
- **Pagers**

DESCRIPTION

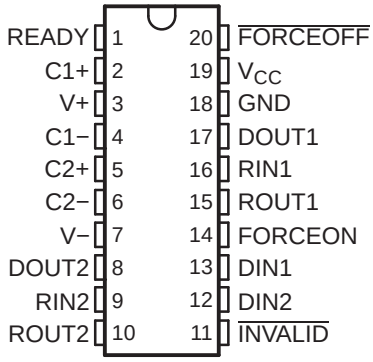
The MAX3318 is a dual-driver, dual-receiver, RS-232 compatible transceiver. The device features auto-power-down plus and enhanced electrostatic discharge (ESD) protection integrated into the chip. Driver output and receiver input are protected to ±8 kV using the IEC 61000-4-2 Air-Gap Discharge method, ±8 kV using the IEC 61000-4-2 Contact Discharge method, and ±15 kV using the Human-Body Model (HBM).

The device operates at a data rate of 460 kbps. The transceiver has a proprietary low-dropout driver output stage enabling RS-232-compatible operation from a 2.25-V to 3-V supply with a dual charge pump. The charge pump requires only four 0.1-µF capacitors and features a logic-level output (READY) that asserts when the charge pump is regulating and the device is ready to begin transmitting.

The MAX3318 achieves a 1-µA supply current using the auto-power-down feature. This device automatically enters a low-power power-down mode when the RS-232 cable is disconnected or the drivers of the connected peripherals are inactive for more than 30 s. The device turns on again when it senses a valid transition at any driver or receiver input. Auto power down saves power without changes to the existing BIOS or operating system.

This device is available in two space-saving packages: 20-pin SSOP and 20-pin TSSOP.

DB OR PW PACKAGE
(TOP VIEW)



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of the Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

DETAILED DESCRIPTION

Flexible control options for power management are featured when the serial port and driver inputs are inactive. The auto-power-down plus feature functions when FORCEON is low and $\overline{\text{FORCEOFF}}$ is high. During this mode of operation, if the device does not sense valid signal transitions on all receiver and driver inputs for approximately 30 s, the built-in charge pump and drivers are powered down, reducing the supply current to 1 µA. By disconnecting the serial port or placing the peripheral drivers off, auto-power-down plus can be disabled when FORCEON and $\overline{\text{FORCEOFF}}$ are high. With auto-power-down plus enabled, the device activates automatically when a valid signal is applied to any receiver or driver input. $\overline{\text{INVALID}}$ is high (valid data) if any receiver input voltage is greater than 2.7 V or less than –2.7 V, or has been between –0.3 V and 0.3 V for less than 30 µs (typical number). $\overline{\text{INVALID}}$ is low (invalid data) if all receiver input voltage are between –0.3 V and 0.3 V for more than 30 µs (typical number).

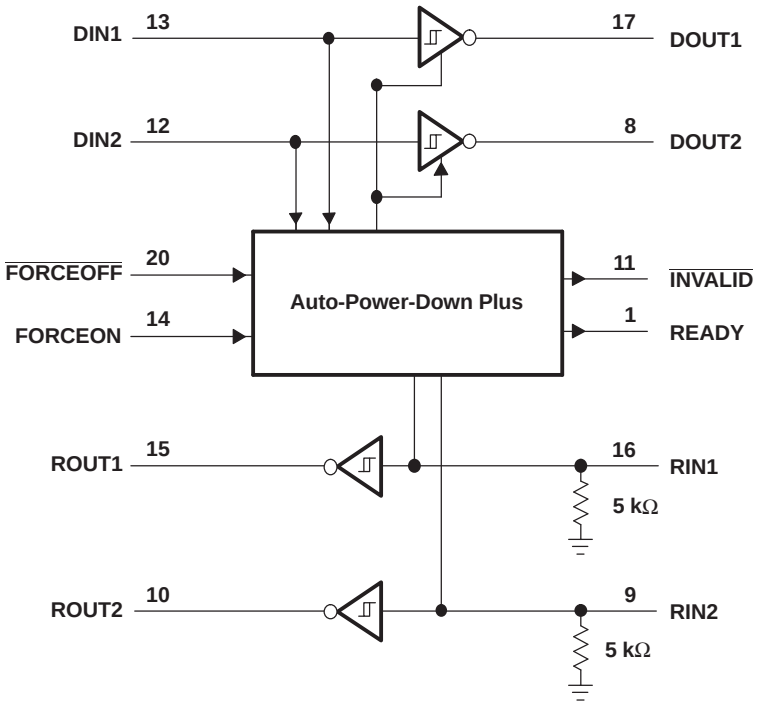
FUNCTION TABLE(1)

INPUT CONDITIONS				OUTPUT STATES				OPERATING MODE
FORCEON	$\overline{\text{FORCEOFF}}$	RECEIVER OR DRIVER EDGE WITHIN 30 s	VALID RS-232 LEVEL PRESENT AT RECEIVER	DRIVER	RECEIVER	$\overline{\text{INVALID}}$	READY	
Auto-Power-Down Plus Conditions								
H	H	No	No	Active	Active	L	H	Normal operation, auto-power-down plus disabled
H	H	No	Yes	Active	Active	H	H	Normal operation, auto-power-down plus disabled
L	H	Yes	No	Active	Active	L	H	Normal operation, auto-power-down plus enabled
L	H	Yes	Yes	Active	Active	H	H	Normal operation, auto-power-down plus enabled
L	H	No	No	Z	Active	L	L	Power down, auto-power-down plus enabled
L	H	No	Yes	Z	Active	H	L	Power down, auto-power-down plus enabled
X	L	X	No	Z	Active	L	L	Manual power down
X	L	X	Yes	Z	Active	H	L	Manual power down
Auto-Power-Down Conditions								
$\overline{\text{INVALID}}$	$\overline{\text{INVALID}}$	X	No	Z	Active	L	L	Power down, auto power down enabled
$\overline{\text{INVALID}}$	$\overline{\text{INVALID}}$	X	Yes	Active	Active	H	H	Normal operation, auto power down enabled

(1) H = high level, L = low level, X = irrelevant, Z = high impedance

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LOGIC DIAGRAM (POSITIVE LOGIC)



TERMINAL FUNCTIONS

TERMINAL		DESCRIPTION
NAME	NO.	
C1+	2	Positive voltage-doubler charge-pump capacitor
C1–	4	Negative voltage-doubler charge-pump capacitor
C2+	5	Positive inverting charge-pump capacitor
C2–	6	Negative inverting charge-pump capacitor
DIN	12, 13	CMOS driver inputs
DOUT	8, 17	RS-232 driver outputs
$\overline{\text{FORCEOFF}}$	20	Force-off input, active low. Drive low to power down transmitters and charge pump. This overrides auto power down and FORCEON (see Function Table).
FORCEON	14	Force-on input, active high. Drive high to override auto power down, keeping transmitters on ($\overline{\text{FORCEOFF}}$ must be high) (see Function Table).
GND	18	Ground
$\overline{\text{INVALID}}$	11	Valid signal detector output, active low. A logic high indicates that a valid RS-232 level is present on a receiver input.
READY	1	Ready to transmit output, active high. READY is enabled high when V– goes below –3.5 V and the device is ready to transmit.
RIN	9, 16	RS-232 receiver inputs
ROUT	10, 15	CMOS receiver outputs
V+	3	$2 \times V_{CC}$ generated by the charge pump
V–	7	$-2 \times V_{CC}$ generated by the charge pump
V_{CC}	19	2.25-V to 3-V single-supply voltage

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Absolute Maximum Ratings(1)

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V_{CC} to GND		–0.3	6	V
V+ to GND(2)		–0.3	7	V
V– to GND(2)		–7	0.3	V
V+ + IV-I(2)			13	V
Input voltage	DIN, FORCEON, $\overline{\text{FORCEOFF}}$ to GND	–0.3	6	V
	RIN to GND		±25	
Output voltage	DOUT to GND		±13.2	V
	ROUT, $\overline{\text{INVALID}}$, READY to GND	–0.3	V_{CC} + 0.3	
Short-circuit duration	DOUT to GND		Continuous	
Continuous power dissipation (T_A = 70°C)	16-pin SSOP (derate 7.14 mW/°C above 70°C)		571	mW
	20-pin SSOP (derate 8 mW/°C above 70°C		640	
	20-pin TSSOP (derate 7 mW/°C above 70°C)		559	
Storage temperature range		–65	150	°C
Lead temperature (soldering, 10 s)			300	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) V+ and V– can have maximum magnitudes of 7 V, but their absolute difference cannot exceed 13 V.

Recommended Operating Conditions

See Figure 4

				MIN	NOM	MAX	UNIT
	Supply voltage			2.25	2.5	3	V
V_{IH}	Driver and control high-level input voltage	DIN, $\overline{\text{FORCEOFF}}$, FORCEON	V_{CC} = 2.5 V to 3 V	0.7 × V_{CC}		5.5	V
V_{IL}	Driver and control low-level input voltage	DIN, $\overline{\text{FORCEOFF}}$, FORCEON	V_{CC} = 2.5 V to 3 V	0		0.3 × V_{CC}	V
V_I	Receiver input voltage			–25		25	V
T_A	Operating free-air temperature	MAX3318C		0		70	°C
		MAX3318I		–40		85	

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Supply Current Section Electrical Characteristics

V_{CC} = 2.25 V to 3 V, C1–C4 = 0.1 µF, $T_A = T_{MIN}$ to T_{MAX} (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP(1)	MAX	UNIT
DC Characteristics (V_{CC} = 2.5 V, T_A = 25°C)					
Auto-power-down plus supply current	FORCEON = GND, $\overline{\text{FORCEOFF}}$ = V_{CC}, All RIN and DIN idle		1	10	µA
Auto-power-down supply current	$\overline{\text{FORCEOFF}}$ = GND		1	10	µA
Supply current	FORCEON = $\overline{\text{FORCEOFF}}$ = V_{CC}, No load		0.3	2	mA

(1) Typical values are at V_{CC} = 2.5 V, T_A = 25°C.

ESD Protection

PARAMETER	TEST CONDITIONS	TYP	UNIT
RIN, DOUT	Human-Body Model (HBM)	±15	kV
	IEC 61000-4-2 Air-Gap Discharge method	±8	
	IEC 61000-4-2 Contact Discharge method	±8	

Driver Section Electrical Characteristics

over recommended ranges of supply voltage and operating free-air temperature,
V_{CC} = 2.25 V to 3 V, C1–C4 = 0.1 µF, $T_A = T_{MIN}$ to T_{MAX} (unless otherwise noted) (see Figure 4)

PARAMETER	TEST CONDITIONS	MIN	TYP(1)	MAX	UNIT
Driver input hysteresis			0.3		V
Input leakage current	FORCEON, DIN, $\overline{\text{FORCEOFF}}$		±0.01	±1	µA
Output voltage swing	All driver outputs loaded with 3 kΩ to ground	±3.7	±4		V
Output resistance	V_{CC} = 0, Driver output = ±2 V	300	10M		Ω
Output short-circuit current(2)			±25	±60	mA
Output leakage current	V_{CC} = 0 or 2.25 V to 3 V, V_{OUT} = ±12 V, Drivers disabled			±25	µA

(1) Typical values are at V_{CC} = 2.5 V, T_A = 25°C.
(2) Short-circuit durations should be controlled to prevent exceeding the device absolute power dissipation ratings, and not more than one output should be shorted at a time.

Driver Section Switching Characteristics

over recommended ranges of supply voltage and operating free-air temperature,
V_{CC} = 2.25 V to 3 V, C1–C4 = 0.1 µF, $T_A = T_{MIN}$ to T_{MAX} (unless otherwise noted) (see Figure 1)

PARAMETER	TEST CONDITIONS	MIN	TYP(1)	MAX	UNIT
Maximum data rate	R_L = 3 kΩ, C_L = 1000 pF, One transmitter switching	460			kbps
$\lvert t_{PHL} - t_{PLH} \rvert$ Driver skew(2)			100		ns
Transition-region slew rate	V_{CC} = 2.5 V, T_A = 25°C, R_L = 3 kΩ to 7 kΩ, Measured from 3 V to –3 V or –3 V to 3 V, C_L = 150 pF to 2500 pF	4		30	V/µs

(1) Typical values are at V_{CC} = 2.5 V, T_A = 25°C.
(2) Pulse skew is defined as $\lvert t_{PLH} - t_{PHL} \rvert$ of each channel of the same device.

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Receiver Section Electrical Characteristics

over recommended ranges of supply voltage and operating free-air temperature, V_{CC} = 2.25 V to 3 V, C1–C4 = 0.1 µF, $T_A = T_{MIN}$ to T_{MAX} (unless otherwise noted) (see Figure 4)

PARAMETER	TEST CONDITIONS	MIN	TYP(1)	MAX	UNIT
Input voltage range		–25		25	V
Input threshold low	T_A = 25°C			0.3 × V_{CC}	V
Input threshold high	T_A = 25°C	0.7 × V_{CC}			V
Input hysteresis			0.3		V
Input resistance	T_A = 25°C	3	5	7	kΩ
Output leakage current			±0.05	±10	µA
Output voltage low	I_{OUT} = 0.5 mA			0.1 × V_{CC}	V
Output voltage high	I_{OUT} = –0.5 mA	0.9 × V_{CC}			V

(1) Typical values are at V_{CC} = 2.5 V, T_A = 25°C.

Receiver Section Switching Characteristics

over recommended ranges of supply voltage and operating free-air temperature, V_{CC} = 2.25 V to 3 V, C1–C4 = 0.1 µF, $T_A = T_{MIN}$ to T_{MAX} (unless otherwise noted) (see Figure 4)

PARAMETER		TEST CONDITIONS	TYP(1)	UNIT
t_{PHL}	Receiver propagation delay	RIN to ROUT, C_L = 150 pF	0.175	µs
t_{PLH}			0.175	
$\lvert t_{PHL} - t_{PLH} \rvert$	Receiver skew(2)		50	ns

(1) Typical values are at V_{CC} = 2.5 V, T_A = 25°C.
(2) Pulse skew is defined as $\lvert t_{PLH} - t_{PHL} \rvert$ of each channel of the same device.

Auto-Power-Down Plus Section Electrical Characteristics

over recommended ranges of supply voltage and operating free-air temperature, V_{CC} = 2.25 V to 3 V, C1–C4 = 0.1 µF, $T_A = T_{MIN}$ to T_{MAX} (unless otherwise noted) (see Figure 4)

PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
Receiver input threshold to $\overline{\text{INVALID}}$ high	Positive threshold		2.7	V
	Negative threshold	–2.7		
Receiver input threshold $\overline{\text{INVALID}}$ low		–0.3	0.3	V
$\overline{\text{INVALID}}$, READY voltage low	I_{OUT} = 0.5 mA		0.1 × V_{CC}	V
$\overline{\text{INVALID}}$, READY voltage high	I_{OUT} = –0.5 mA	0.8 × V_{CC}		V

Auto-Power-Down Plus Section Switching Characteristics

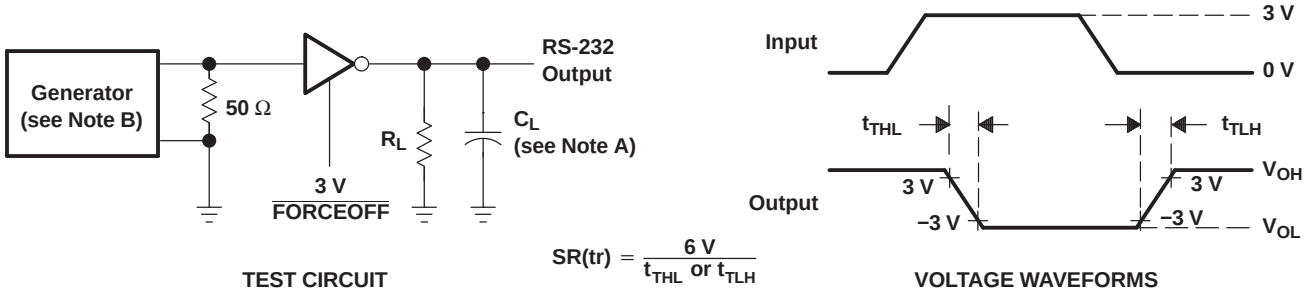
over recommended ranges of supply voltage and operating free-air temperature, V_{CC} = 2.25 V to 3 V, C1–C4 = 0.1 µF, $T_A = T_{MIN}$ to T_{MAX} (unless otherwise noted) (see Figure 4)

PARAMETER		TEST CONDITIONS	MIN	TYP(1)	MAX	UNIT
t_{INVH}	Receiver positive or negative threshold to $\overline{\text{INVALID}}$ high	V_{CC} = 2.5 V		1		µs
t_{INVL}	Receiver positive or negative threshold to $\overline{\text{INVALID}}$ low	V_{CC} = 2.5 V		30		µs
t_{WU}	Receiver or driver edge to driver enabled	V_{CC} = 2.5 V		100		µs
$t_{AUTOPRDN}$	Receiver or driver edge to driver shutdown	V_{CC} = 2.5 V	15	30	60	s

(1) Typical values are at V_{CC} = 2.5 V,T_A = 25°C.

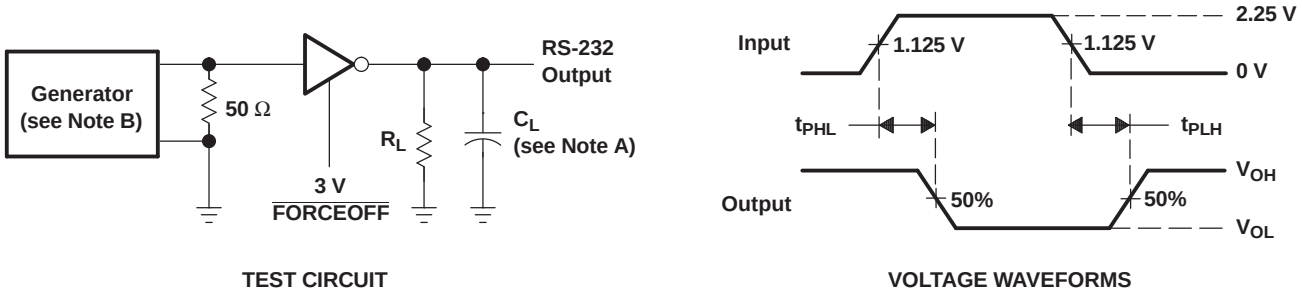
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PARAMETER MEASUREMENT INFORMATION



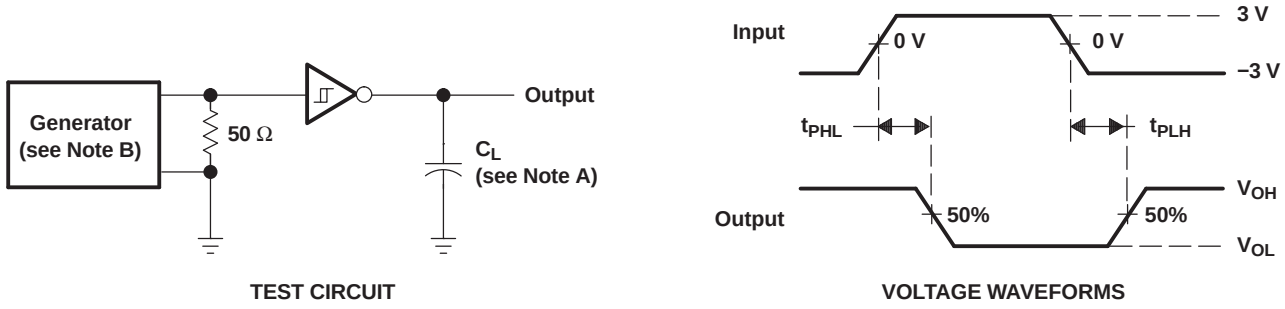
NOTES: A. C_L includes probe and jig capacitance.
B. The pulse generator has the following characteristics: PRR = 250 kbit/s, Z_O = 50 Ω, 50% duty cycle, $t_r \le 10$ ns, $t_f \le 10$ ns.

Figure 1. Driver Slew Rate



NOTES: A. C_L includes probe and jig capacitance.
B. The pulse generator has the following characteristics: PRR = 250 kbit/s, Z_O = 50 Ω, 50% duty cycle, $t_r \le 10$ ns, $t_f \le 10$ ns.

Figure 2. Driver Pulse Skew

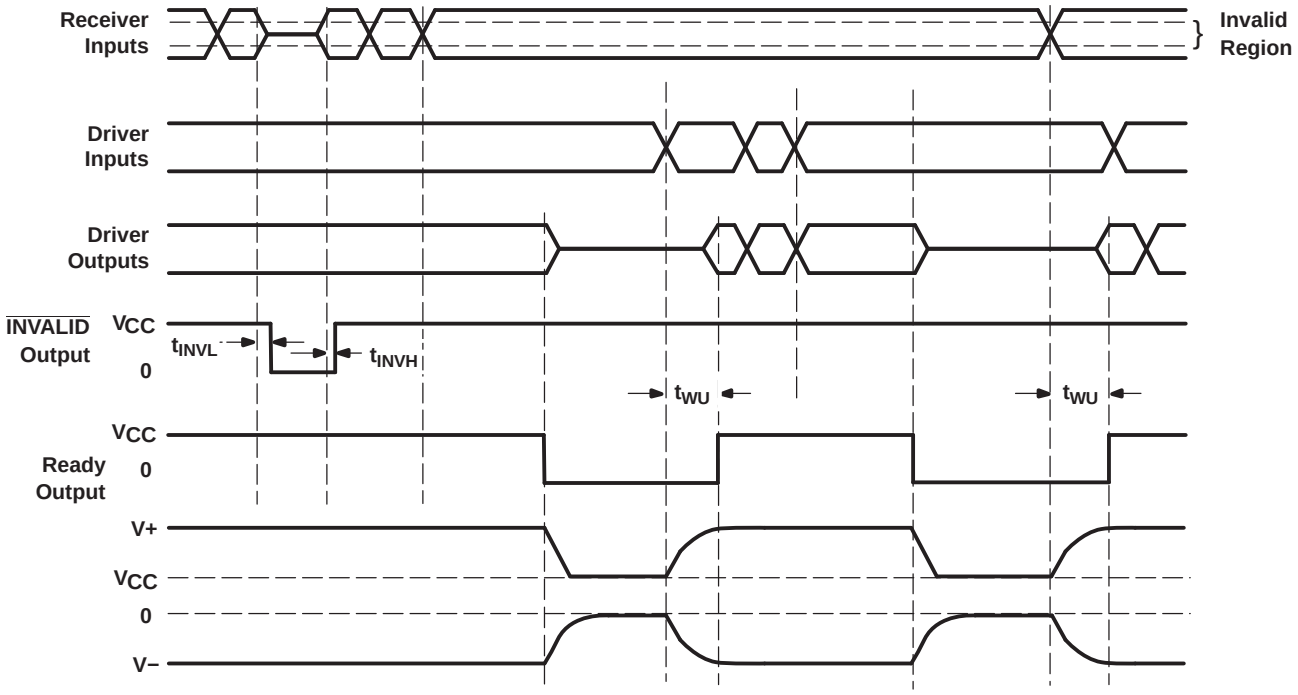


NOTES: A. C_L includes probe and jig capacitance.
B. The pulse generator has the following characteristics: Z_O = 50 Ω, 50% duty cycle, $t_r \le 10$ ns, $t_f \le 10$ ns.

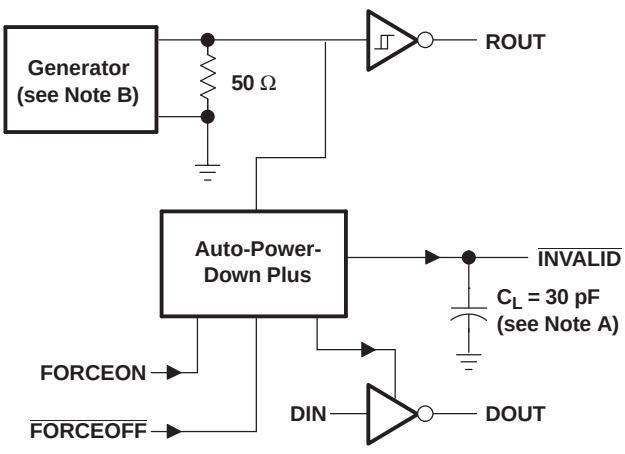
Figure 3. Receiver Propagation Delay Times

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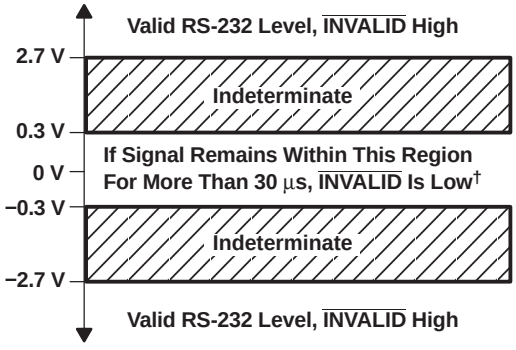
PARAMETER MEASUREMENT INFORMATION



VOLTAGE WAVEFORMS



TEST CIRCUIT



† Auto power down disables drivers and reduces supply current to 1 µA.

Figure 4. INVALID Propagation Delay Times and Supply Enabling Time

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PARAMETER MEASUREMENT INFORMATION

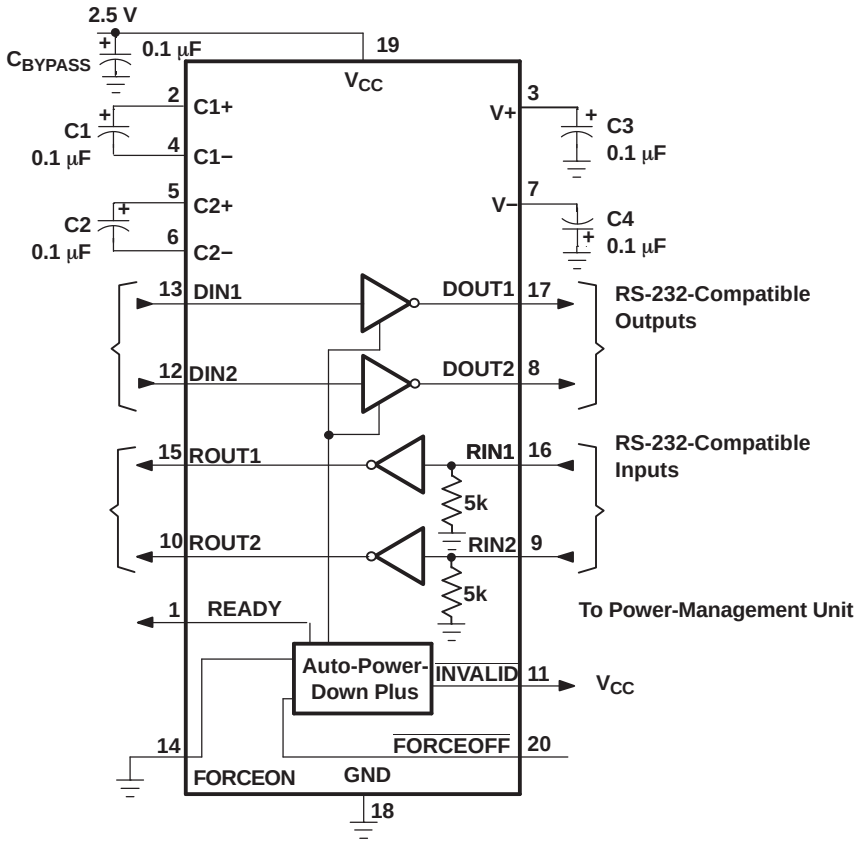


Figure 5. Typical Application Circuit

REVISION HISTORY

Changes from Original (June 2006) to Revision A **Page**

- Updated document to new TI datasheet format - no specification changes. 1
- Removed Ordering Information Table. 2
- Updated TERMINAL FUNCTIONS table to fix inconsistency. 3

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
MAX3318CDB	ACTIVE	SSOP	DB	20	70	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	MP318C	Samples
MAX3318CDBR	ACTIVE	SSOP	DB	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	MP318C	Samples
MAX3318CDBRG4	ACTIVE	SSOP	DB	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	MP318C	Samples
MAX3318CPW	ACTIVE	TSSOP	PW	20	70	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	MP318C	Samples
MAX3318CPWR	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	MP318C	Samples
MAX3318IDB	ACTIVE	SSOP	DB	20	70	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MP318I	Samples
MAX3318IDBR	ACTIVE	SSOP	DB	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MP318I	Samples
MAX3318IPW	ACTIVE	TSSOP	PW	20	70	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MP318I	Samples
MAX3318IPWR	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MP318I	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

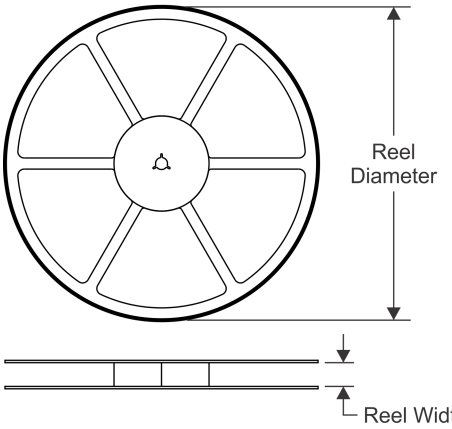
(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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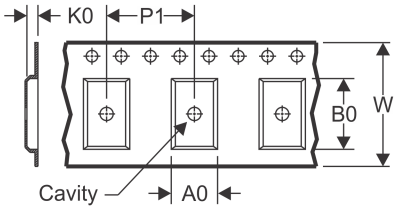
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TAPE AND REEL INFORMATION

REEL DIMENSIONS

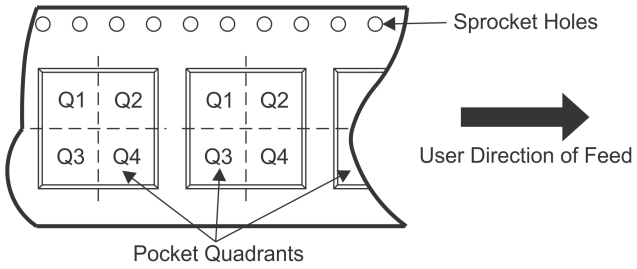


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

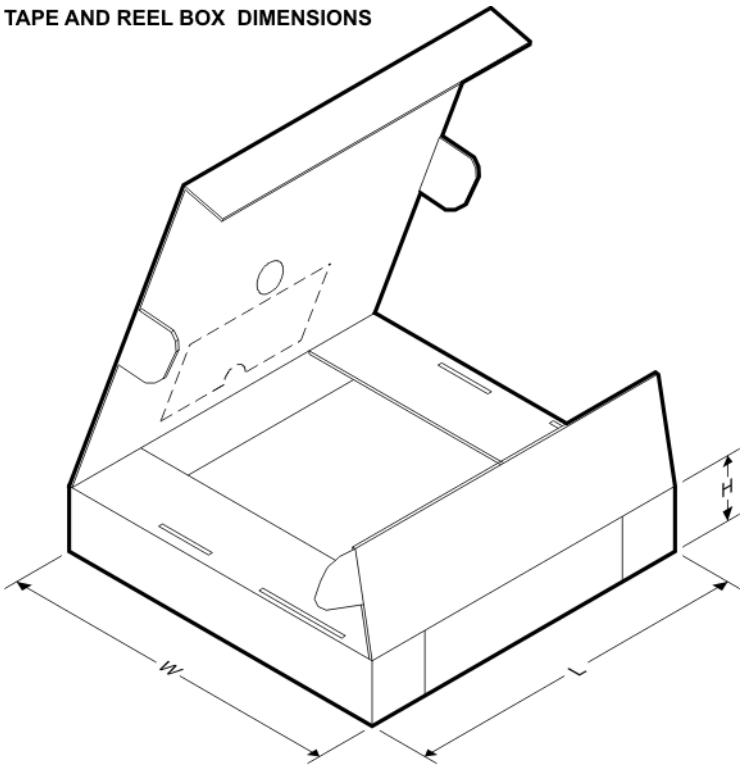
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
MAX3318CDBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
MAX3318CPWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1
MAX3318IDBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
MAX3318IPWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1

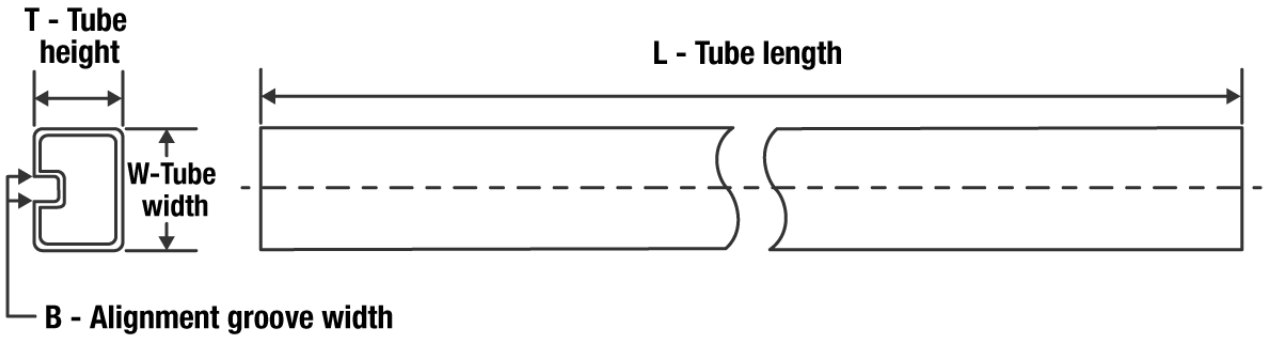
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
MAX3318CDBR	SSOP	DB	20	2000	853.0	449.0	35.0
MAX3318CPWR	TSSOP	PW	20	2000	853.0	449.0	35.0
MAX3318IDBR	SSOP	DB	20	2000	853.0	449.0	35.0
MAX3318IPWR	TSSOP	PW	20	2000	853.0	449.0	35.0

TUBE



*All dimensions are nominal

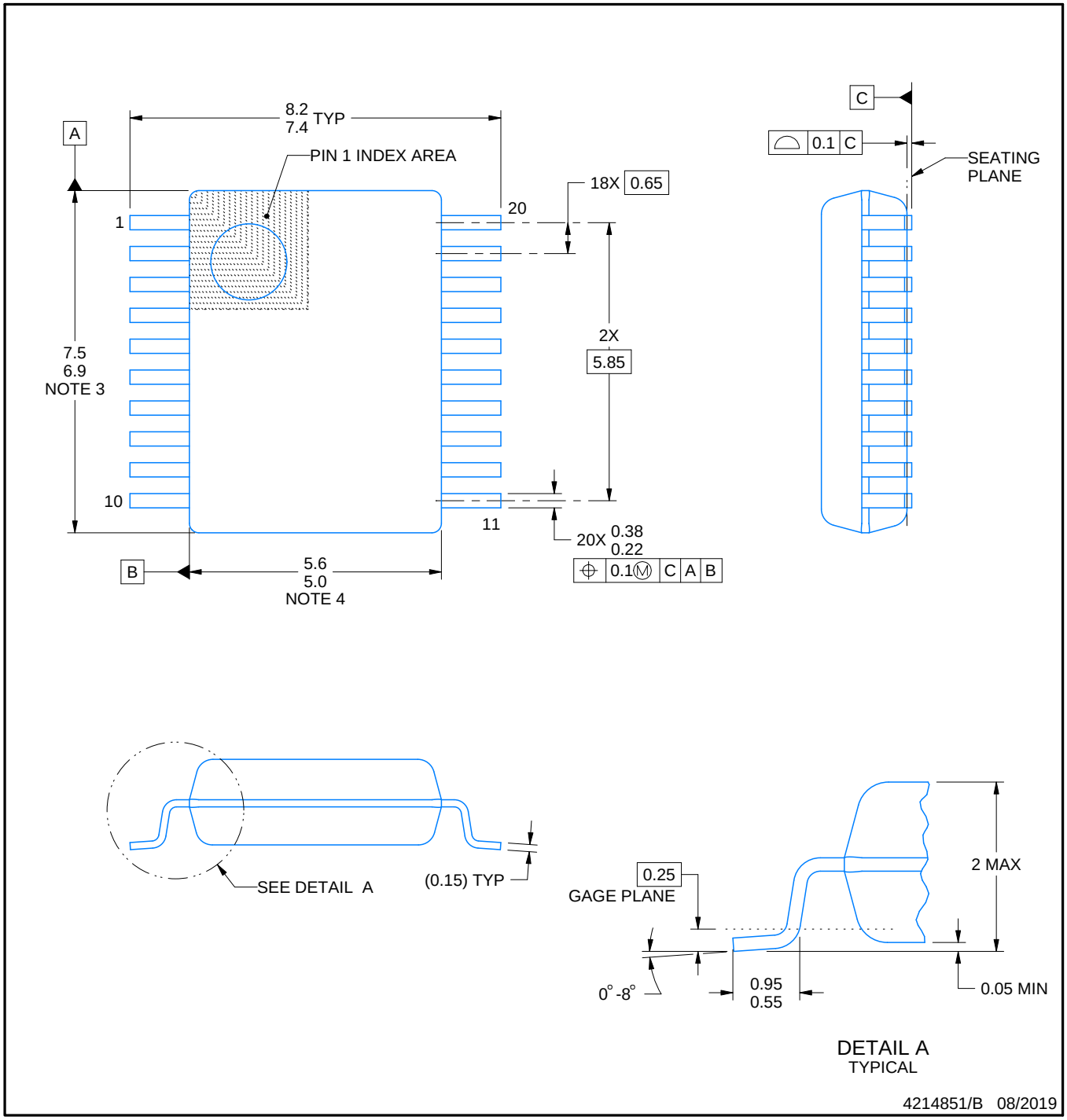
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
MAX3318CDB	DB	SSOP	20	70	530	10.5	4000	4.1
MAX3318CPW	PW	TSSOP	20	70	530	10.2	3600	3.5
MAX3318IDB	DB	SSOP	20	70	530	10.5	4000	4.1
MAX3318IPW	PW	TSSOP	20	70	530	10.2	3600	3.5

PACKAGE OUTLINE

DB0020A

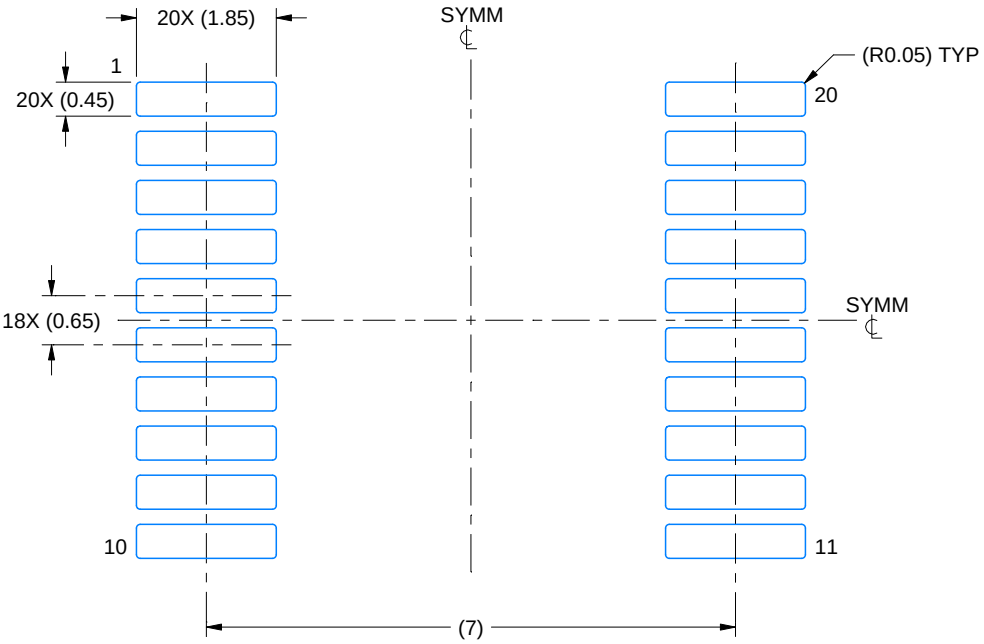
SSOP - 2 mm max height

SMALL OUTLINE PACKAGE

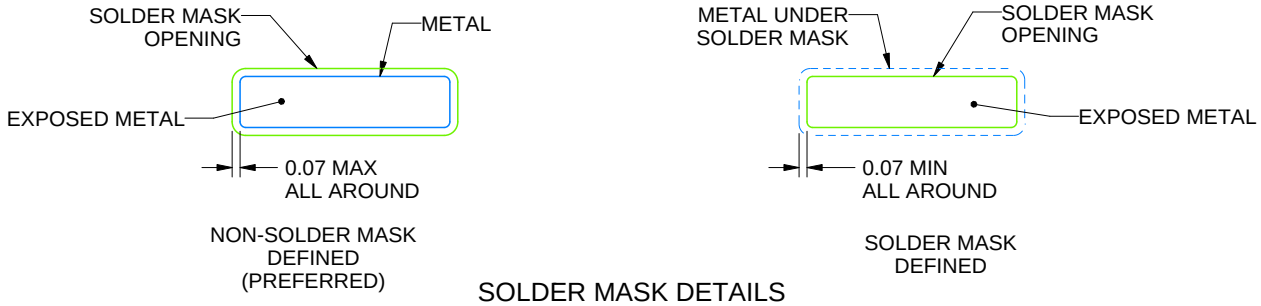


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-150.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

4214851/B 08/2019

NOTES: (continued)

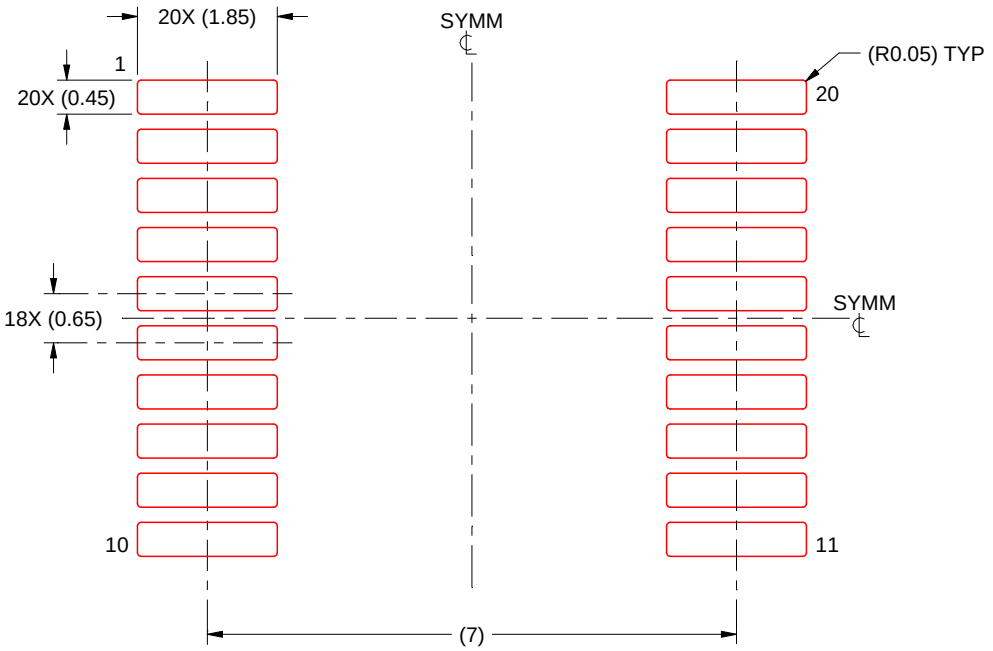
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4214851/B 08/2019

NOTES: (continued)

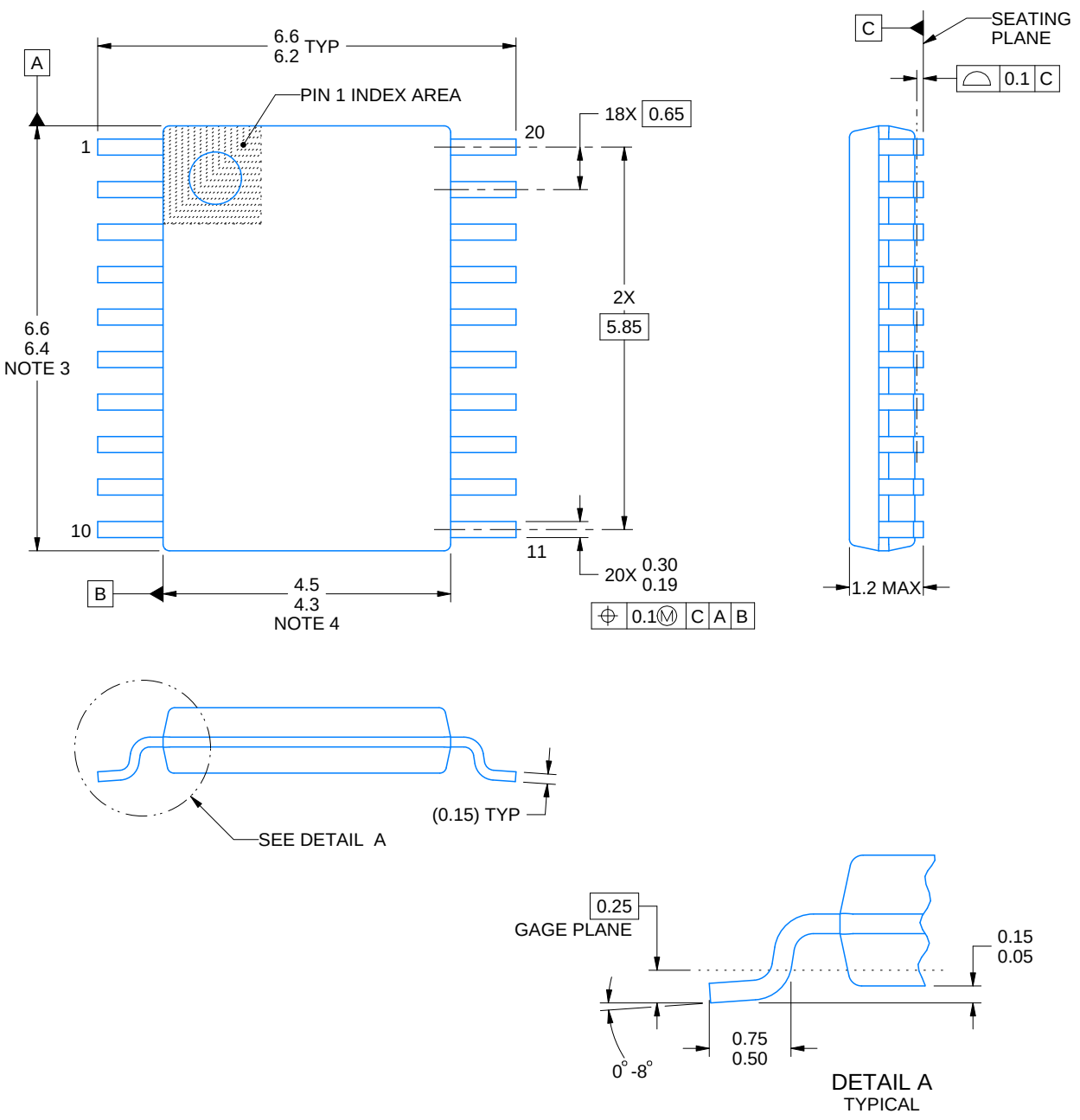
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PACKAGE OUTLINE

PW0020A

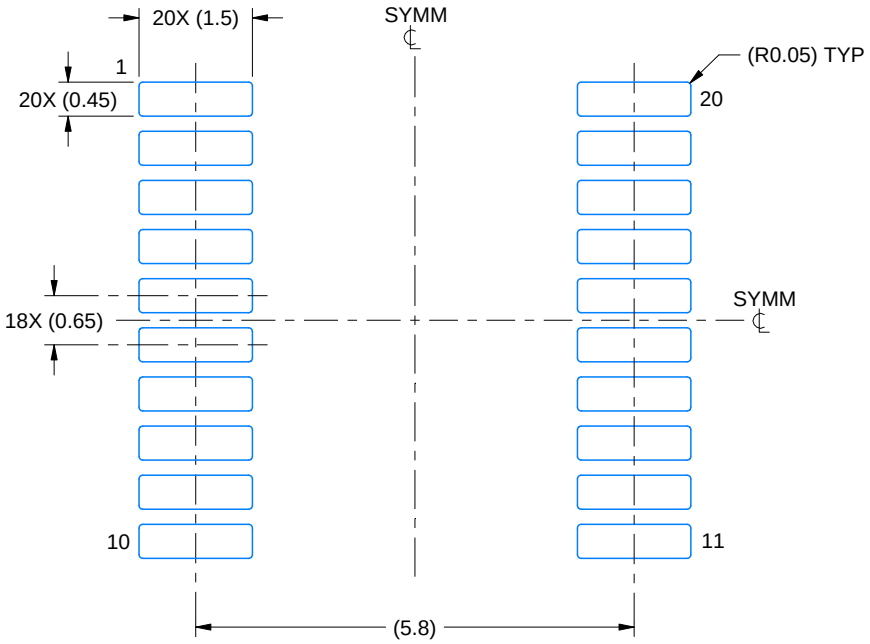
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

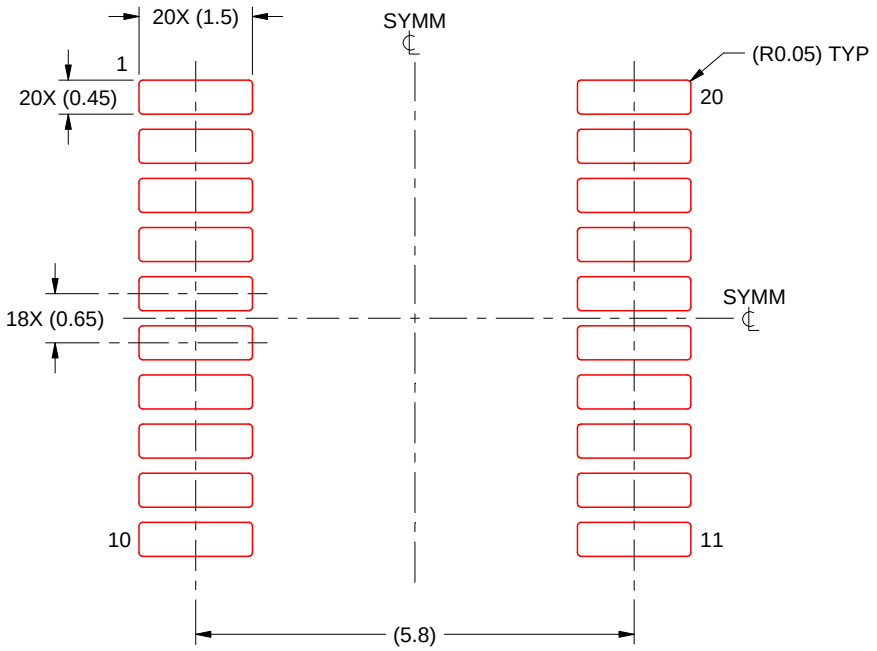


SOLDER MASK DETAILS

4220206/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



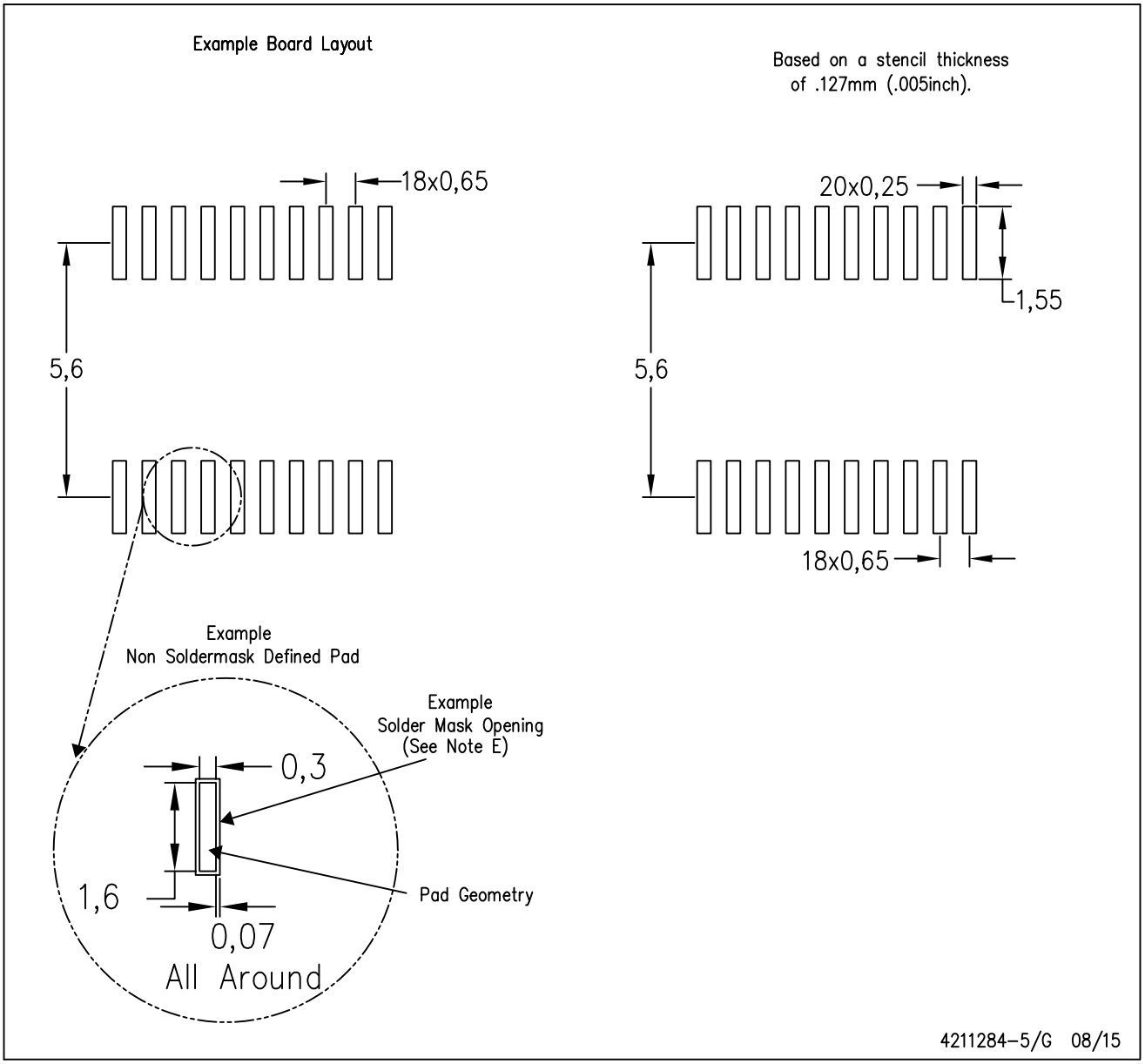
SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220206/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PW (R–PDSO–G20) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate design.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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